

Form PTO-1449
(Rev. 2-88)

APPLICATION NO.
10/082,010

APPLICANT
SINGH, et al.

FILING DATE
2/22/02

GROUP

[illegible]

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION		
						YES	NO	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		Stöber, W., et al. "Controlled Growth of Monodisperse Silica Spheres in the Micron Size Range", <i>Journal of Colloid and Interface Science</i> , Vol. 26 (1968), pgs. 62-69; and
LOT 116		Rosen, M.J., "Surfactants and Interfacial Phenomena" John Wiley & Sons, 1989, pgs. 3-32, 52-54, 70-80, 122-132 and 398-401.
LOT 117		

EXAMINER <i>Lynette J. Woz - Emmuni</i>	DATE CONSIDERED <i>11/13/2003</i>
<p>* EXAMINER: Initial if a citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>	

WP089907;1

RECEIVED
JUN -7 2002
TECHNOLOGY CENTER 2800

Form PTO-1449
(Rev. 2-88)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
5853-224APPLICATION NO.
10/082,010INFORMATION DISCLOSURE STATEMENT
BY APPLICANTAPPLICANT
Singh et al.FILING DATE
02/22/2002

GROUP

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

EXAMINER'S INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
L.T.M.-E	5,954,997	09/21/1999	Kaufman et al.	252	79.1	
L.T.M.-E	6,454,819 B1	09/24/2002	Yano et al.	51	298	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	Country	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

L.T.M.-E		Luo et al., "CHEMICAL-MECHANICAL POLISHING OF COPPER IN ACIDIC MEDIA," CMP-MIC Conference, 145-151, 1996

EXAMINER

Lynette J. Umeg-Eronini

DATE CONSIDERED

11/5/2003

* EXAMINER: Initial if a citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.